

Application Serial No. 10/800,603
Reply to Notice of May 4, 2006

PATENT
Docket: CU-3637

Amendments To The Claims

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

Listing of claims:

1. (previously presented) A semiconductor device substrate, comprising:
a substrate body having a wiring layer;
a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and
a reinforcing member having two surfaces and sides,
wherein the surface areas of the reinforcing member are larger than the opening forming portion,
wherein the sides and one surface area of the reinforcing member are embedded in said substrate body at a portion corresponding to the opening forming portion such that only a portion of the unembedded surface is exposed through the opening forming portion, and
a semiconductor element mounted on the surface of the reinforcing member exposed through the opening forming portion.
2. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer.
3. (original) The semiconductor device substrate as claimed in claim 2, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

Application Serial No. 10/800,603
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Docket: CU-3637

4. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is an interposer having a via that directly electrically connects the semiconductor element and the wiring layer.
5. (original) The semiconductor device substrate as claimed in claim 4, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
6. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
7. (previously presented) A manufacturing method of a substrate, said manufacturing method comprising the steps of:
 - manufacturing a reinforcing member having two surfaces and sides;
 - arranging the reinforcing member on a base at a portion corresponding to an opening forming portion of the base, wherein the surface areas of the reinforcing member are larger than the opening forming portion;
 - forming a substrate body on the base on which the reinforcing member is arranged so that the reinforcing member is provided in said substrate, said substrate body including a wiring layer and made of a material that is different from a material of the base,
 - wherein the sides and one surface area of the reinforcing member are embedded in said substrate body at a portion corresponding to the opening forming portion such that only a portion of the unembedded surface is exposed through the opening forming portion
 - mounting a semiconductor element on the surface of the reinforcing member exposed through the opening forming portion.

Application Serial No. 10/800,603
Reply to Notice of May 4, 2006

PATENT
Docket: CU-3637

8. (original) The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a capacitor on a core member.
9. (previously presented) The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a via penetrating the core member.
10. (original) The manufacturing method as claimed in claim 9, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
11. (original) The manufacturing method as claimed in claim 8, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
12. (original) The manufacturing method as claimed in claim 7, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
13. (currently amended) A semiconductor device ~~substrate~~ comprising:
a substrate body having a wiring layer;
a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and
a reinforcing member having two surfaces and sides,
wherein the surface areas of the reinforcement member are larger than the opening forming portion,
wherein the sides and one surface area of the reinforcing member are embedded in said substrate body at a portion corresponding to the opening forming portion such that only a portion of the unembedded surface is exposed through the opening forming

Application Serial No. 10/800,603
Reply to Notice of May 4, 2006

PATENT
Docket: CU-3637

portion, and

a semiconductor element mounted on the surface of the reinforcing member exposed through the opening forming portion.

14. (previously presented) A semiconductor device of claim 13, wherein the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer.

15. (previously presented) A semiconductor device of claim 14, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

16. (previously presented) A semiconductor device of claim 13, wherein the reinforcing member is an interposer having a via that directly electrically connects the semiconductor element and the wiring layer.

17. (previously presented) A semiconductor device of claim 16, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

18. (previously presented) A semiconductor device of claim 13, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

19. (cancelled)